

ABSTRACT OF THE DISCLOSURE

A heat-softening heat-radiation sheet including a polyolefin-based heat-conductive composition which comprises a polyolefin and a heat-conductive filler, has a softening point of 40°C or above, has a thermal conductivity of 1.0 W/mK or higher, has a viscosity at 80°C of from  $1 \times 10^2$  to  $1 \times 10^5$  Pa·s and has a plasticity at 25°C in the range of from 100 to 700. This heat-radiation sheet which is in the form of a solid sheet at room temperature, can readily be attached to or detached from electronic components and a heat sink, is capable of softening by the heat generated during operation of electronic components, to have the interfacial contact thermal resistance at a negligible level, and has a superior heat-radiation performance.

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0973924-101121